

# 2A, 200V-1000V Fast Recovery Surface Mount Rectifiers

#### **FEATURES**

- Glass passivated junction chip
- Ideal for automated placement
- Low power loss, high efficiency
- Fast switching for high efficiency
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

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- High frequency rectification
- Freewheeling application
- Switching mode converters and inverters, computer and telecommunication.

#### **MECHANICAL DATA**

- Case: Thin SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Pure tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.029 g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	2	Α		
$V_{RRM}$	200 -1000	V		
I <sub>FSM</sub>	50	Α		
T <sub>J MAX</sub>	150	°C		
Package	Thin SMA			
Configuration	Single Die			









Thin SMA

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)								
PARAMETER		SYMBOL	RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	UNIT
Marking code on the devi	ce		RS2DAL	RS2GAL	RS2JAL	RS2KAL	RS2MAL	
Repetitive peak reverse v	oltage	$V_{RRM}$	200	400	600	800	1000	V
Reverse voltage, total rms value		V <sub>R(RMS)</sub>	140	280	420	560	700	V
Forward current		I <sub>F</sub>	2				Α	
Surge peak forward current, single half sine-	8.3ms at T <sub>A</sub> = 25°C		50				Α	
wave superimposed on rated load per diode	1.0ms at T <sub>A</sub> = 25°C	I <sub>FSM</sub>	140				Α	
Junction temperature		TJ	-55 to +150				°C	
Storage temperature		T <sub>STG</sub>	-55 to +150			°C		

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	16	°C/W		
Junction-to-ambient thermal resistance	R <sub>OJA</sub>	73	°C/W		
Junction-to-case thermal resistance	R <sub>OJC</sub>	14	°C/W		

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

PARAMET	ER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C		0.93	-	V
	RS2DAL	I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		1.01	1.30	V
	RS2GAL RS2JAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.78	-	V
Famuurd valtaga (1)		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		0.88	1.02	V
Forward voltage <sup>(1)</sup>		I <sub>F</sub> = 1.0A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.98	-	V
	RS2KAL	I <sub>F</sub> = 2.0A, T <sub>J</sub> = 25°C		1.06	1.30	V
	RS2MAL	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C		0.83	-	V
		I <sub>F</sub> = 2.0A, T <sub>J</sub> = 125°C		0.93	1.05	V
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>		T <sub>J</sub> = 25°C	1	-	1	μΑ
		T <sub>J</sub> = 125°C	- I <sub>R</sub>	-	40	μΑ
	RS2DAL RS2GAL		t <sub>rr</sub>	-	150	ns
Reverse recovery time	RS2JAL	I <sub>F</sub> =0.5A,I <sub>R</sub> =1.0A, Irr=0.25A		-	250	ns
	RS2KAL RS2MAL	0.2071		-	500	ns
Junction capacitance	RS2DAL RS2GAL RS2JAL	1 MHz, V <sub>R</sub> =4.0V	CJ	11	-	pF
	RS2KAL RS2MAL			10	-	pF

### Notes:

- (1) Pulse test with PW=0.3 ms
- (2) Pulse test with PW=30 ms

ORDERING INFORMATION					
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING			
RS2xAL M3G	Thin SMA	3,500 / 7" reel			
RS2xAL M2G	Thin SMA	14,000 / 13" reel			

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# Notes:

(1) "x" defines voltage from 200V(RS2DAL) to 1000V(RS2MAL)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

Fig.1 Forward Current Derating Curve

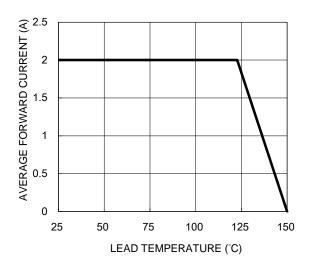


Fig.3 Typical Reverse Characteristics

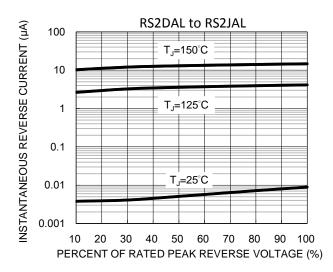


Fig.5 Typical Reverse Characteristics

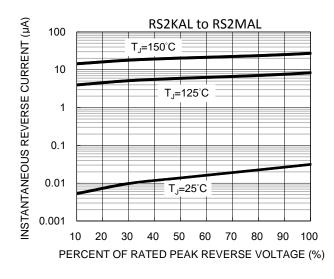


Fig.2 Typical Junction Capacitance

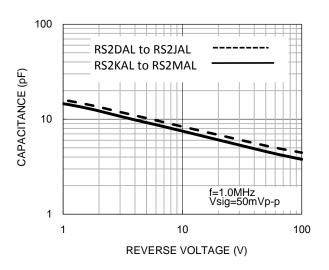
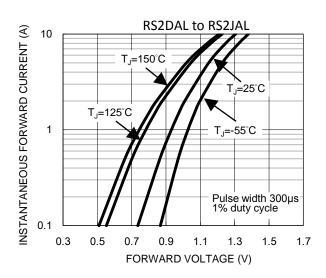
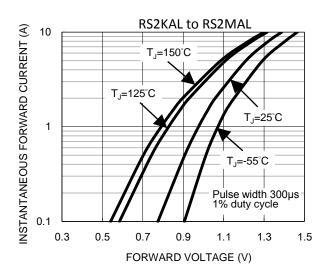


Fig.4 Typical Forward Characteristics



**Fig.6 Typical Forward Characteristics** 





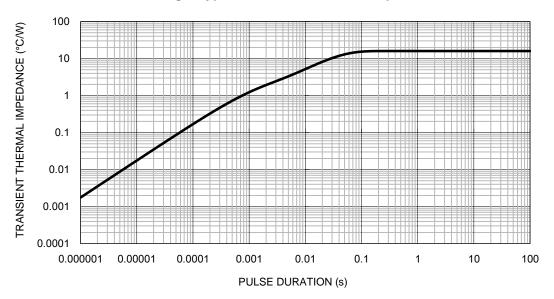
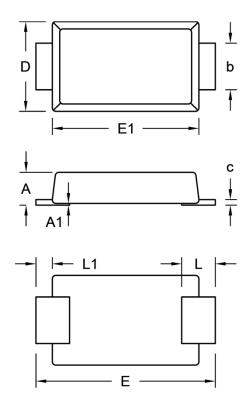


Fig.7 Typical Transient Thermal Impedance



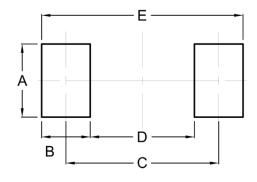
## **PACKAGE OUTLINE DIMENSIONS**

Thin SMA



DIM.	Unit	(mm)	Unit (inch)		
Dilvi.	Min.	Max.	Min.	Max.	
Α	0.90	1.00	0.035	0.039	
A1	0.00	0.10	0.000	0.004	
b	1.25	1.45	0.049	0.057	
С	0.10	0.22	0.004	0.009	
D	2.50	2.70	0.098	0.106	
E	5.05	5.35	0.199	0.211	
E1	4.15	4.35	0.163	0.171	
L	0.75	1.20	0.030	0.047	
L1	0.30	0.60	0.012	0.024	

## **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	2.10	0.083
В	1.40	0.055
С	4.40	0.173
D	3.00	0.118
E	5.80	0.228

## **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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